

Atty. Docket No. PIA31223/DBE/US
Serial No: 10/751,212

Amendments to the Claims

Please amend the claims as follows:

1. (Currently amended) A method for packaging a semiconductor device, comprising the steps of:
 - (a) forming an Au bump on a bond pad of a wafer;
 - (b) dicing the wafer into a chip; and
 - (c) attaching the Au bump of the chip to a substrate to form a flip-chip bonding by bond using a thermo-pressure process;
 - ~~—(d) encapsulating the flip-chip bonding by using a nonconductive epoxy; and~~
 - ~~—(e) sawing the substrate to singulate individual packages.~~
2. (Original) The method of claim 1, wherein, in the step (c), the Au bump is connected to the substrate through an Ag layer and a Cu layer.
3. (New) The method of claim 1, further comprising the step of
 - (d) encapsulating the flip-chip bond using a nonconductive epoxy after step (c).
4. (New) The method of claim 3, further comprising the step of
 - (e) sawing the substrate to singulate individual packages.